

<b>PCN Number:</b>	20170125001	<b>PCN Date:</b>	Jan 27, 2017
<b>Title:</b>	Qualification of FFAB as additional Fab site option for select devices		
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Dept:</b>	Quality Services
<b>Proposed 1<sup>st</sup> Ship Date:</b>	Apr 27, 2017	<b>Estimated Sample Availability:</b>	Date provided at sample request.
<b>Change Type:</b>			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material
<input checked="" type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials
		<input type="checkbox"/>	Part number change
<input type="checkbox"/>		<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>		<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>		<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

**PCN Details**

**Description of Change:**

Texas Instruments is pleased to announce the qualification of its FFAB fabrication facility as an additional Wafer Fab source for the selected devices listed in the "Product Affected" section.

Current Fab Site			Additional Fab Site		
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter
RFAB	LBC7	300 mm	FFAB	LBC7	200 mm

Qual details are provided in the Qual Data Section.

**Reason for Change:**

Continuity of Supply

**Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):**

None

**Changes to product identification resulting from this PCN:**

**Current:**

Current Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
RFAB	RFB	USA	Richardson

**New Fab Site:**

New Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
<b>FR-BIP-1</b>	<b>TID</b>	<b>DEU</b>	<b>Freising</b>

Sample product shipping label (not actual product label)

TEXAS INSTRUMENTS  
 MADE IN: Malaysia  
 2DC: 2Q:  
 MSL 2 / 260C/1 YEAR SEAL DT  
 MSL 1 / 235C/UNLIM 03/29/04  
 OPT:  
 ITEM: 39  
 LBL: 5A (L)T0:1750

(1P) SN74LS07NSR  
 (Q) 2000 (D) 0336  
 (31T) LOT: 3959047MLA  
 (4W) TKY (1T) 7523483S12  
 (P)  
 (2P) REV: (V) 0053317  
 (20L) CSO: SHE (21L) CCO: USA  
 (22L) ASO: MLA (23L) ACO: MYS

**Product Affected:**

TAS5754MDCA	TAS5756MDCAR	TAS5768MDCA	TAS880021DCA
TAS5754MDCAR	TAS5766MDCA	TAS5768MDCAR	TAS880021DCAR
TAS5756MDCA	TAS5766MDCAR		

## Qualification Report

### LBC7 G2TPA3127A0IN offload from RFAB to FFAB

**Approve Date 12-Sep-2016**

#### Product Attributes

Attributes	Qual Device: TA S880021DCA	QBS Product Reference: TA S880021DCA_A0	QBS Process Reference: TCA6416PW
Assembly Site	TAI	TAI	MLA
Package Family	HTSSOP	HTSSOP	TSSOP
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V 0
Wafer Fab Supplier	FFAB, RFAB	RFAB	FFAB
Wafer Fab Process	1833C05, LBC7	1833C05, LBC7	LBC7

- QBS: Qual By Similarity
- Qual Device TAS880021DCA is qualified at LEVEL3-260C
- Device TAS880021DCA contains multiple dies.

#### Qualification Results

**Data Displayed as: Number of lots / Total sample size / Total failed**

Type	Test Name / Condition	Duration	Qual Device: TA S880021DCA	QBS Product Reference: TA S880021DCA_A0	QBS Process Reference: TCA6416PW
AC	Autoclave 121C	96 Hours	-	1/77/0	3/231/0
CDM	ESD - CDM	1500 V	-	1/3/0	-
ED	Electrical Characterization	Per Datasheet Parameters	Pass	Pass	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	3/231/0
HBM	ESD - HBM	2500 V	-	1/3/0	-
HTOL	Life Test, 150C	300 Hours	-	-	3/321/0
HTSL	High Temp Storage Bake 150C	1000 Hours	-	-	3/231/0
LU	Latch-up	( per JESD78 )	-	1/6/0	-
TC	Temperature Cycle, - 65/150C	500 Cycles	-	1/77/0	3/231/0
WBP	Bond Pull	Wires	1/76/0	1/76/0	-
WBS	Ball Bond Shear	Wires	1/76/0	1/76/0	-

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

**Green/Pb-free Status:**

Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

Location	E-Mail
USA	<a href="mailto:PCNAmericasContact@list.ti.com">PCNAmericasContact@list.ti.com</a>
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Asia Pacific	<a href="mailto:PCNAsiaContact@list.ti.com">PCNAsiaContact@list.ti.com</a>
Japan	<a href="mailto:PCNJapanContact@list.ti.com">PCNJapanContact@list.ti.com</a>